

L Number	Hits	Search Text	DB	Time stamp
2	94	(430.clas. and solder) and bump and plat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/09 08:53
3	425	((((228/180.21,180.22).CCLS.) and solder) and bump) and (plat\$4)	USPAT; US-PGPUB; DERWENT	2003/12/09 09:09
4	324	((((438/612).CCLS.) and solder) and bump) and (plat\$4)	USPAT; US-PGPUB; DERWENT	2003/12/09 09:17
-	12595	(pad or BLM or UBM) same metall\$6	USPAT; US-PGPUB; DERWENT	2003/03/06 15:15
-	9034	solder near bump	USPAT; US-PGPUB; DERWENT	2003/03/06 15:15
-	54	((pad or BLM or UBM) same metall\$6) and (solder near bump) and (electro\$5plat\$3 and (solder and Cu and Ni and Ag and Au))	USPAT; US-PGPUB; DERWENT	2003/03/06 15:37
-	327	electro\$5plat\$3 and (solder and Cu and Ni and Ag and Au)	USPAT; US-PGPUB; DERWENT	2003/03/06 17:04